



## Material Content Data Sheet



<b>Sales Product Name</b>				BSC010N04LSI		<b>Issued</b>		25. September 2017	
<b>MA#</b>				MA000974064					
<b>Package</b>				PG-TDSON-8-17		<b>Weight*</b>		119.16 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.517	1.27	1.27	12733	12733	
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		317		
	inorganic material	phosphorus	7723-14-0	0.011	0.01		95		
	non noble metal	copper	7440-50-8	37.762	31.70	31.74	316892	317304	
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	373	373	
encapsulation	organic material	carbon black	1333-86-4	0.086	0.07		719		
	plastics	epoxy resin	-	6.079	5.10		51015		
	inorganic material	silicondioxide	60676-86-0	36.646	30.75	35.92	307530	359264	
leadfinish	non noble metal	tin	7440-31-5	1.470	1.23	1.23	12334	12334	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1389	1389	
solder	noble metal	silver	7440-22-4	0.053	0.04		442		
	non noble metal	tin	7440-31-5	0.042	0.04		353		
	non noble metal	lead	7439-92-1	2.010	1.69	1.77	16872	17667	
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	zinc	7440-66-6	0.013	0.01		113		
	non noble metal	iron	7439-89-6	0.269	0.23		2255		
	non noble metal	copper	7440-50-8	10.909	9.15	9.39	91547	93943	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		55		
	non noble metal	zinc	7440-66-6	0.026	0.02		222		
	non noble metal	iron	7439-89-6	0.529	0.44		4440		
	non noble metal	copper	7440-50-8	21.482	18.03	18.50	180276	184993	
*deviation	< 10%		Sum in total:			100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com